MA2C029W

Silicon epitaxial planar type

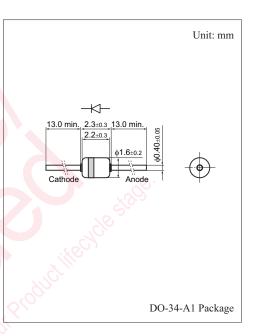
For reduced voltage and temperature compensation

Features

- High reliability achieved through combination of a planar type chip and glass sealing structure
- Easy mounting because of employing DO-35 (DHD) envelope
- Extremely small reverse current I_R
- Large power dissipation P_D
- Wide forward voltage V_F range

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V _R	6	V
Peak forward current	I _{FM}	100	mA
Power dissipation	P _D	150	mW
Junction temperature	Tj	150	°C
Storage temperature	T _{stg}	-55 to +150	°C



Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C^{*1}$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward current	V _{F1}	$I_R = 10 \ \mu A$	0.77) V		V
	V _{F2}	$I_F = 3 \text{ mA}$	A	*2		v
Reverse current	IR	$V_R = 6 V$	X.		1.0	μΑ
Temperature coefficient of forward voltage *3	$-\Delta V_F/V_T$	$I_F = 3 \text{ mA}$		4.6		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. *1: The temperature must be controlled 25°C for V_F mesurement. V_F value measured at other temperature must be adjusted to V_F (25°C)

*2:	Туре	V _F (V)
	MA2C029WA	1.18 to 1.28
	MA2C029WB	1.26 to 1.36

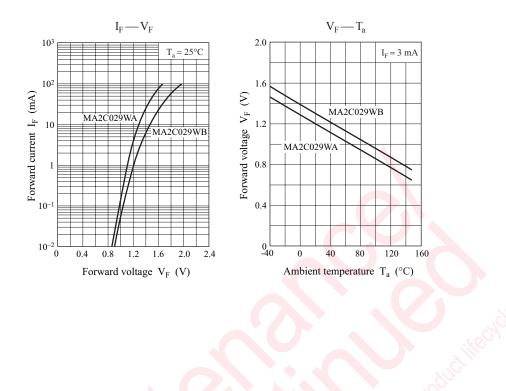
*3: $T_i = 25^{\circ}C$ to $150^{\circ}C$

Cathode Indication

Type No.	MA2C029WA	MA2C029WB
Color	Light blue	Brown

MA2C029W

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